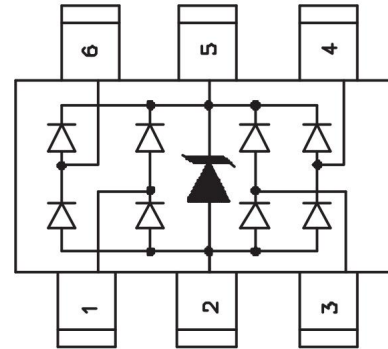


Features

- 150 watts peak pulse power per line($t_P=8/20\mu s$)
- Protects four I/O lines
- Low clamping voltage
- Low operating voltage
- Low capacitance



MAIN APPLICATIONS

- USB 2.0&3.0 power and data line protection
- Digital video interface (DVI)
- Notebook computers
- Video graphics cards
- Monitors and flat panel displays
- 10/ 100/ 1000 ethernet
- SIM ports
- ATM interfaces

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD) $\pm 20kV$ (air), $\pm 20kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 5A (8/20 μs)

ABSOLUTE MAXIMUM RATINGS (TA=25°C , RH=45%-75%, unless otherwise noted)

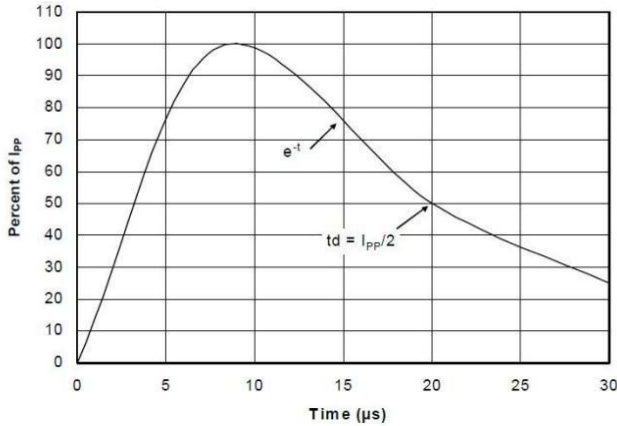
Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20µs waveform	P _{PP}	150	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 20 +/-20	kV
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (TA=25°C)

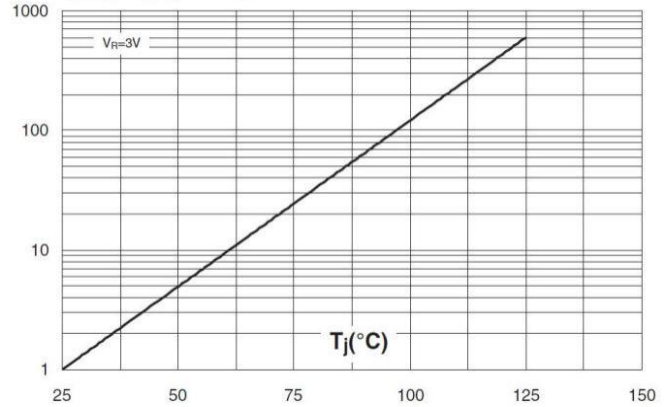
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}				5.0	V
Reverse breakdown voltage	V _{BR}	I _T =1mA	6.0			V
Reverse leakage current	I _R	V _{RWM} =5V			1	µA
Forward voltage	V _F	I _T =10mA		0.8	1.0	V
Clamping voltage (I/O pin to Ground)	V _C	I _{PP} =1A, t _P =8/20µs		9.5	11	V
	V _C	I _{PP} =5A, t _P =8/20µs		12.5	15	
Junction capacitance	C _J	V _{RWM} =0V, f=1MHz Any I/O pin to Ground		0.65	0.8	pF
		V _{RWM} =0V, f=1MHz Between I/O pins		0.3	0.5	

Typical characteristics @ Ta=25°C unless otherwise specified

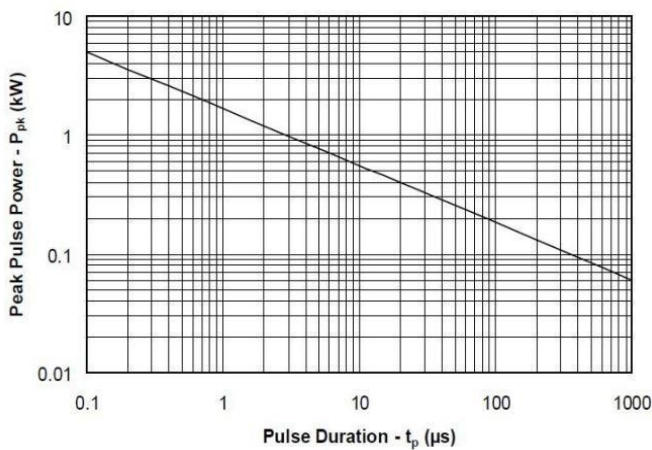
Pulse Waveform



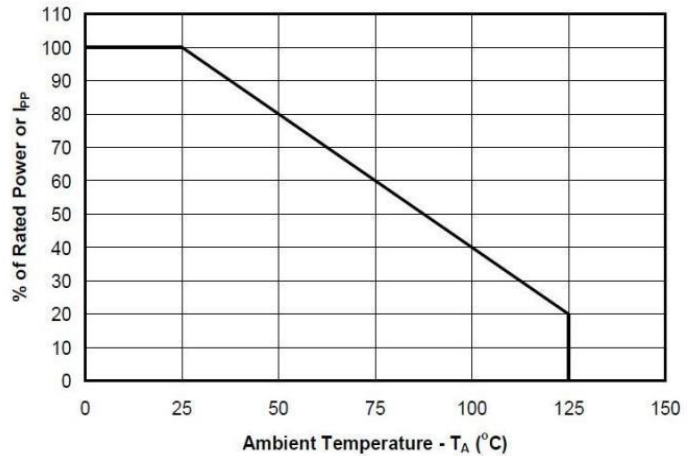
$I_R[T_j] / I_R[T_j=25^\circ\text{C}]$



Non-Repetitive Peak Pulse Power vs. Pulse Time

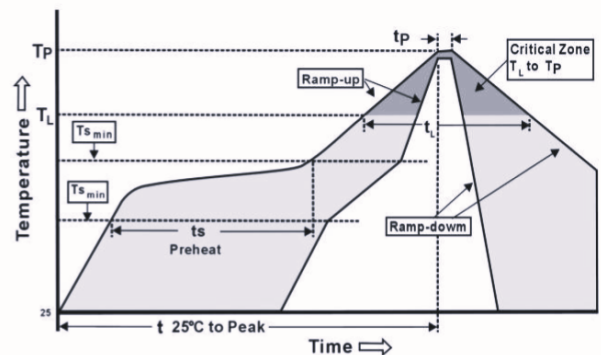


Power Derating Curve

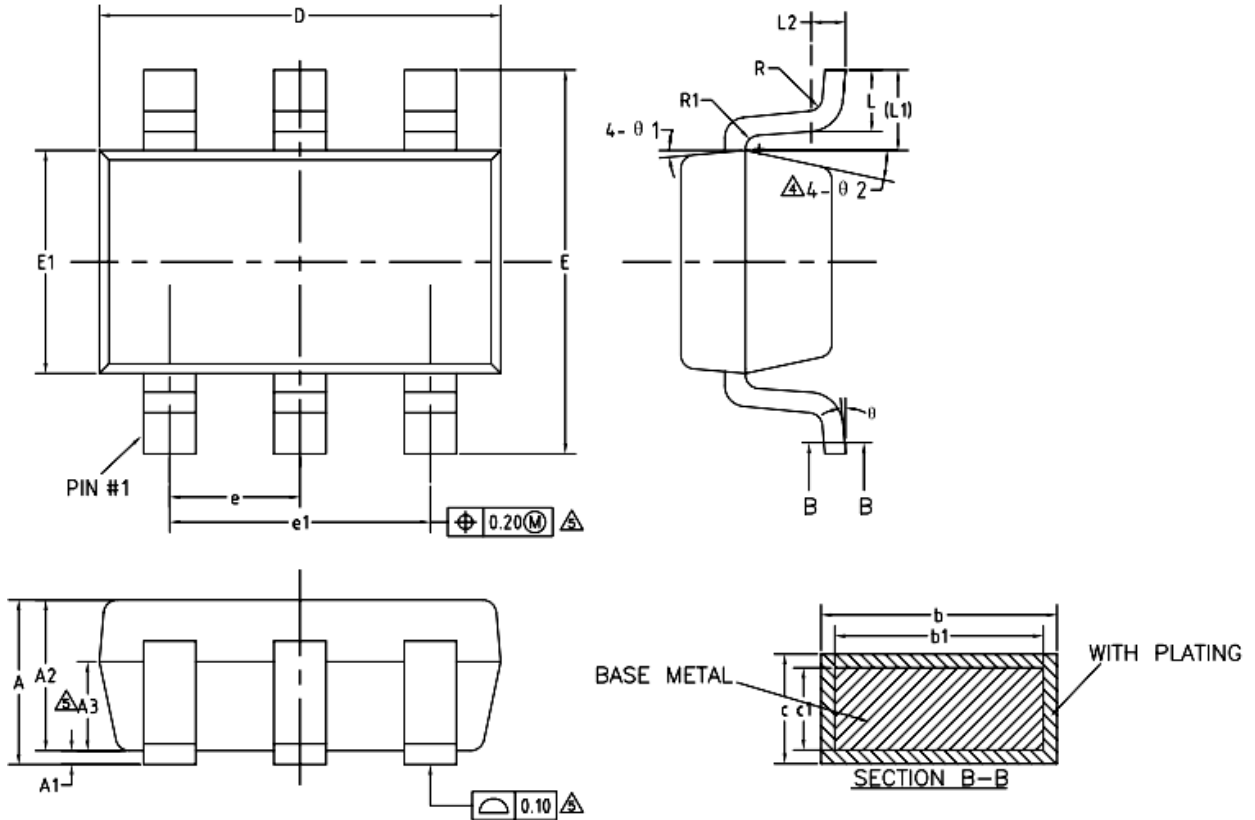


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(\text{Min})}$)	150°C
	- Temperature Max ($T_{s(\text{Max})}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second Max
$T_{s(\text{Max})}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



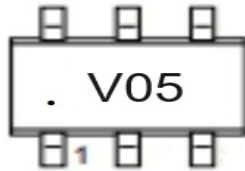
SOT23-6



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	—	—	1.25
A1	0	—	0.15
A2	1.00	1.10	1.20
A3	0.60	0.65	0.70
b	0.36	—	0.50
b1	0.36	0.38	0.45
c	0.14	—	0.20
c1	0.14	0.15	0.16
D	2.826	2.926	3.026
E	2.60	2.80	3.00
E1	1.526	1.626	1.726
e	0.90	0.95	1.00
e1	1.80	1.90	2.00
L	0.35	0.45	0.60
L1	0.59REF		
L2	0.25BSC		
R	0.10	—	—
R1	0.10	—	0.20
θ	0°	—	8°
θ_1	3°	5°	7°
θ_2	6°	—	14°

Marking



Ordering information

Order code	Package	Base qty	Delivery mode
UMW PDWL050019	SOT23-6	3000	Tape and reel

单击下面可查看定价，库存，交付和生命周期等信息

[>>UMW\(友台半导体\)](#)